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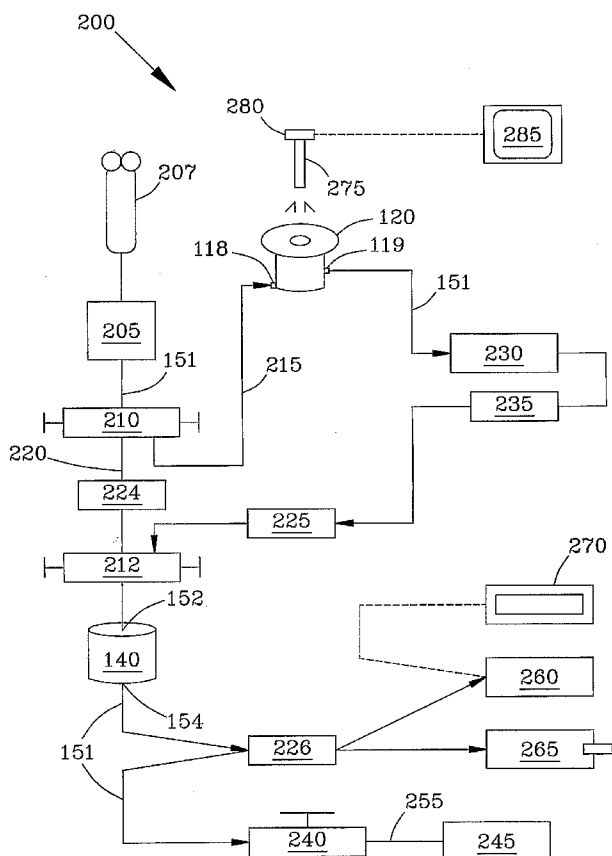
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(54) Title: REACTIVE FLUID SYSTEMS FOR REMOVING DEPOSITION MATERIALS AND METHODS FOR USING SAME



(57) Abstract: The present invention generally relates to methods for processing materials. More particularly, the present invention relates to reactive fluids and uses thereof for removing deposition materials, including, but not limited to, overburden materials, metals, non-metals, layered materials, organics, polymers, and semiconductor materials. The instant invention finds application in such commercial processes as semiconductor chip manufacturing.

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